

BGU7041

1 GHz wideband low-noise amplifier

Rev. 2 — 13 September 2011

Product data sheet

1. Product profile

1.1 General description

The BGU7041 MMIC is a 3.3 V wideband amplifier with internal biasing. It is designed specifically for high linearity, low-noise applications over a frequency range of 40 MHz to 1 GHz. It is especially suited for Set-Top Box applications.

The LNA is housed in a 6-pin SOT363 plastic SMD package.

1.2 Features and benefits

- Voltage supply of 3.3 V
- Internally biased
- Gain of 10 dB
- Flat gain between 40 MHz and 1 GHz
- Noise figure of 3.8 dB
- High linearity with an $IP3_O$ of 29 dBm
- 75 Ω input and output impedance
- ESD protection > 2 kV Human Body Model (HBM) and > 1.5 kV Charged Device Model (CDM) on all pins

1.3 Applications

- Terrestrial Silicon and cable Set-Top Boxes (STB)
- Silicon and “Can” tuners
- Personal Video Recorders (PVR) and Digital Video Recorders (DVR)
- Home networking and in-house signal distribution



1.4 Quick reference data

Table 1. Quick reference data
T_{amb} = 25 °C; typical values at V_{CC} = 3.3 V; Z_S = Z_L = 75 Ω; R_{bias} = 7.5 Ω; 40 MHz ≤ f₁ ≤ 1000 MHz.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage	RF input AC coupled	3.1	3.3	3.5	V
I _{CC(tot)}	total supply current		-	38	-	mA
T _{amb}	ambient temperature		-10	-	+70	°C
NF	noise figure		-	3.8	-	dB
P _{L(1dB)}	output power at 1 dB gain compression	1 GHz	-	12	-	dBm
IP3 _O	output third-order intercept point		[1]	29	-	dBm

[1] The fundamental frequency (f₁) is 1000 MHz. The intermodulation product (IM3) is 2 × f₂ − f₁, where f₂ = f₁ ± 1 MHz. Input power P_i = −10 dBm.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	RF_OUT		
2	V _{CC}		
3	n.c.		
4	n.c.		
5	GND		
6	RF_IN		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BGU7041	-	plastic surface-mounted package; 6 leads	SOT363

4. Marking

Table 4. Marking

Type number	Marking code	Description
BGU7041	*VA	* = p : made in Hong Kong
		* = W : made in China
		* = t : made in Malaysia

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage	RF input AC coupled	-0.6	3.5	V
I _{CC(tot)}	total supply current	configurable with external resistor	-	60	mA
P _{tot}	total power dissipation	T _{sp} ≤ 100 °C	[1]	250	mW
P _i	input power	single tone	-	10	dBm
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-10	+70	°C
V _{ESD}	electrostatic discharge voltage	Human Body Model (HBM); according to JEDEC standard 22-A114E	2	-	kV
		Charged Device Model (CDM); according to JEDEC standard 22-C101B	1.5	-	kV

[1] T_{sp} is the temperature at the solder point of the ground lead.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
R _{th(j-sp)}	thermal resistance from junction to solder point		240	K/W

7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C; typical values at V_{CC} = 3.3 V; Z_S = Z_L = 75 Ω; R_{bias} = 7.5 Ω; 40 MHz ≤ f₁ ≤ 1000 MHz.

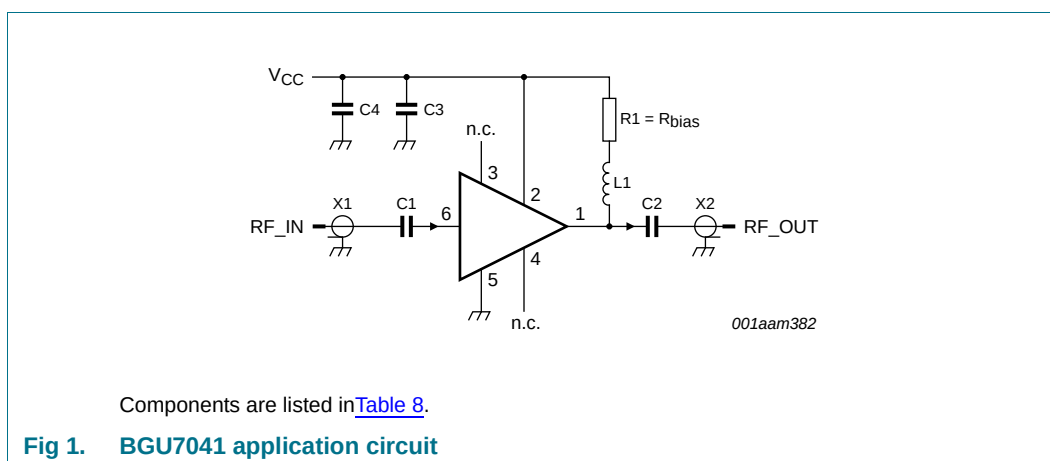
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage	RF input AC coupled	3.1	3.3	3.5	V
I _{CC(tot)}	total supply current		-	38	-	mA
S ₂₁ ²	insertion power gain		-	10		dB
SL _{sl}	slope straight line		-	-1	-	dB
FL	flatness of frequency response		-	0.2	-	dB
NF	noise figure		-	3.8	-	dB
RL _{in}	input return loss		-	21	-	dB
RL _{out}	output return loss		-	12	-	dB
P _{L(1dB)}	output power at 1 dB gain compression	1 GHz	-	12	-	dBm
IP3 _O	output third-order intercept point		[1]	29	-	dBm

[1] The fundamental frequency (f₁) is 1000 MHz. The intermodulation product (IM3) is 2 × f₂ - f₁, where f₂ = f₁ ± 1 MHz. Input power P_i = -10 dBm.

8. Application information

Other applications are possible. Please contact your local sales representative for more information. Application notes are available on the NXP website.

8.1 Application circuit



All control and supply lines must be decoupled properly. The decoupling capacitors must be placed as close to the device as possible.

8.2 Application circuit board layout

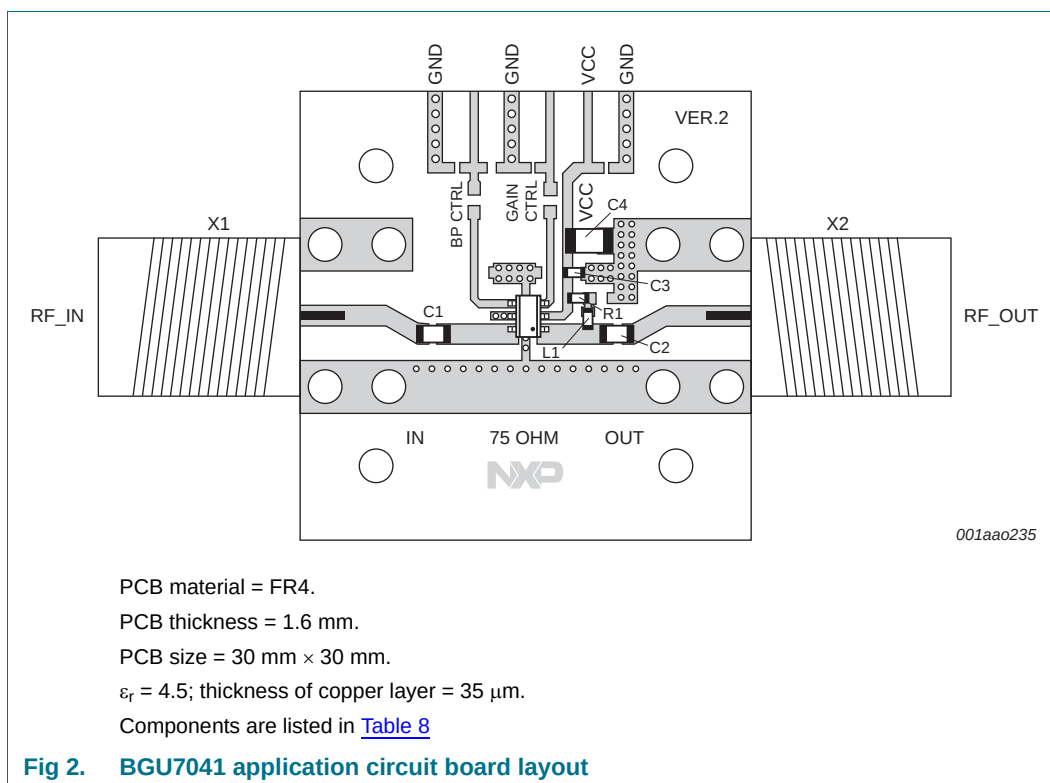


Table 8. List of componentsSee [Figure 1](#) and [Figure 2](#)

Component	Description	Value	Remarks	Function
C1, C2	capacitor	10 nF		DC blocking
C3	capacitor	10 nF		decoupling
C4	capacitor	10 μ F		decoupling
L1	chip ferrite bead	1.5 k Ω	[1] Murata BLM18HE152SN1DF	RF choke
R1	resistor	7.5 Ω	[1] R _{bias}	bias setting
X1, X2	connector	75 Ω	F-connector, edge mount PCB reflow type, Bomar 861V509ERG	input/output

[1] L1 and R1 must have a power rating of 0.1 W or higher.

9. Package outline

Plastic surface-mounted package; 6 leads SOT363

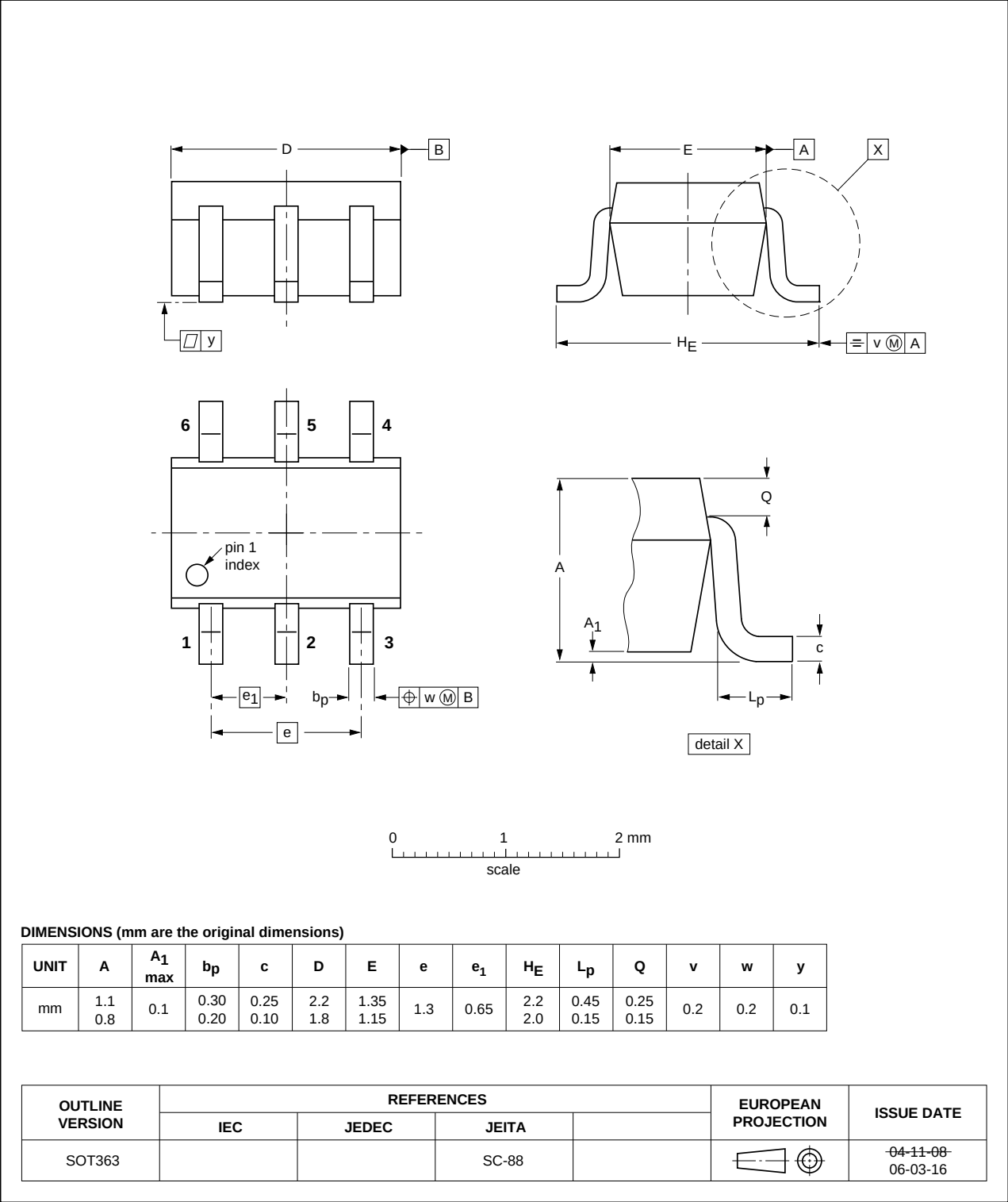


Fig 3. Package outline SOT363

10. Abbreviations

Table 9. Abbreviations

Acronym	Description
AC	Alternating Current
DC	Direct Current
ESD	ElectroStatic Discharge
LNA	Low-Noise Amplifier
MMIC	Monolithic Microwave Integrated Circuit
PCB	Printed-Circuit Board
RF	Radio Frequency
SMD	Surface Mounted Device

11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGU7041 v.2	20110913	Product data sheet		BGU7041 v.1
Modifications:	• Noise figure value updated			
BGU7041 v.1	20110629	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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